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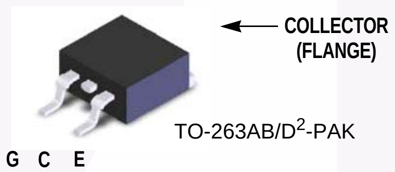
March 2015

FGB20N60SFD
600 V, 20 A Field Stop IGBT

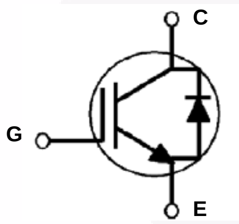
Features
- High Current Capability
- Low Saturation Voltage: $V_{CE(sat)}$ = 2.2 V @ I_C = 20 A
- High Input Impedance
- Fast Switching : E_{OFF} = 8 uJ/A
- RoHS Compliant

Applications
- Solar Inverter, UPS, Welder, PFC

General Description
Using novel field stop IGBT technology, Fairchild's field stop IGBTs offer the optimum performance for solar inverter, UPS, welder and PFC applications where low conduction and switching losses are essential.



TO-263AB/D^2-PAK



Absolute Maximum Ratings

Symbol	Description		Ratings	Unit
V_{CES}	Collector to Emitter Voltage		600	V
V_{GES}	Gate to Emitter Voltage		±20	V
	Transient Gate-to-Emitter Voltage		±30	
I_C	Collector Current	@ T_C = 25°C	40	A
	Collector Current	@ T_C = 100°C	20	A
$I_{CM\ (1)}$	Pulsed Collector Current	@ T_C = 25°C	60	A
I_F	Diode Forward Current	@ T_C = 25°C	20	A
	Diode Forward Current	@ T_C = 100°C	10	A
$I_{FM(1)}$	Pulsed Diode Maximum Forward Current		60	A
P_D	Maximum Power Dissipation	@ T_C = 25°C	208	W
	Maximum Power Dissipation	@ T_C = 100°C	83	W
T_J	Operating Junction Temperature		-55 to +150	°C
T_{stg}	Storage Temperature Range		-55 to +150	°C
T_L	Maximum Lead Temp. for soldering Purposes, 1/8" from case for 5 seconds		300	°C

Notes:
1: Repetitive rating: Pulse width limited by max. junction temperature

Thermal Characteristics

Symbol	Parameter	Typ.	Max.	Unit
$R_{\theta JC}$(IGBT)	Thermal Resistance, Junction to Case	-	0.6	$^oC/W$
$R_{\theta JC}$(Diode)	Thermal Resistance, Junction to Case	-	2.6	$^oC/W$
$R_{\theta JA}$	Thermal Resistance, Junction to Ambient (PCB Mount)(2)	-	40	$^oC/W$

Notes:
2: Mounted on 1" square PCB (FR4 or G-10 material)

Package Marking and Ordering Information

Part Number	Top Mark	Package	Packing Method	Reel Size	Tape Width	Quantity
FGB20N60SFD	FGB20N60SFD	D^2-PAK	Reel	13" Dia	N/A	800

Electrical Characteristics of the IGBT T_C = 25°C unless otherwise noted

Symbol	Parameter	Test Conditions	Min.	Typ.	Max.	Unit
Off Characteristics						
BV_{CES}	Collector to Emitter Breakdown Voltage	V_{GE} = 0 V, I_C = 250 μA	600	-	-	V
ΔBV_{CES} / ΔT_J	Temperature Coefficient of Breakdown Voltage	V_{GE} = 0 V, I_C = 250 μA	-	0.6	-	$V/^oC$
I_{CES}	Collector Cut-Off Current	$V_{CE} = V_{CES}$, V_{GE} = 0 V	-	-	250	μA
I_{GES}	G-E Leakage Current	$V_{GE} = V_{GES}$, V_{CE} = 0 V	-	-	±400	nA
On Characteristics						
$V_{GE(th)}$	G-E Threshold Voltage	I_C = 250 μA, $V_{CE} = V_{GE}$	4.0	5.0	6.5	V
$V_{CE(sat)}$	Collector to Emitter Saturation Voltage	I_C = 20 A, V_{GE} = 15 V	-	2.2	2.8	V
		I_C = 20 A, V_{GE} = 15 V, $T_C = 125^oC$	-	2.4	-	V
Dynamic Characteristics						
C_{ies}	Input Capacitance	V_{CE} = 30 V, V_{GE} = 0 V, f = 1 MHz	-	940	-	pF
C_{oes}	Output Capacitance		-	110	-	pF
C_{res}	Reverse Transfer Capacitance		-	40	-	pF
Switching Characteristics						
$t_{d(on)}$	Turn-On Delay Time	V_{CC} = 400 V, I_C = 20 A, R_G = 10 Ω, V_{GE} = 15 V, Inductive Load, $T_C = 25^oC$	-	13	-	ns
t_r	Rise Time		-	16	-	ns
$t_{d(off)}$	Turn-Off Delay Time		-	90	-	ns
t_f	Fall Time		-	24	48	ns
E_{on}	Turn-On Switching Loss		-	0.37	-	mJ
E_{off}	Turn-Off Switching Loss		-	0.16	-	mJ
E_{ts}	Total Switching Loss		-	0.53	-	mJ
$t_{d(on)}$	Turn-On Delay Time	V_{CC} = 400 V, I_C = 20 A, R_G = 10 Ω, V_{GE} = 15 V, Inductive Load, $T_C = 125^oC$	-	12	-	ns
t_r	Rise Time		-	16	-	ns
$t_{d(off)}$	Turn-Off Delay Time		-	95	-	ns
t_f	Fall Time		-	28	-	ns
E_{on}	Turn-On Switching Loss		-	0.4	-	mJ
E_{off}	Turn-Off Switching Loss		-	0.28	-	mJ
E_{ts}	Total Switching Loss		-	0.69	-	mJ

Electrical Characteristics of the IGBT T_C = 25°C unless otherwise noted

Q_g	Total Gate Charge	V_{CE} = 400 V, I_C = 20 A, V_{GE} = 15 V	-	65	-	nC
Q_{ge}	Gate to Emitter Charge		-	7	-	nC
Q_{gc}	Gate to Collector Charge		-	33	-	nC

Electrical Characteristics of the Diode T_C = 25°C unless otherwise noted

Symbol	Parameter	Test Conditions		Min.	Typ.	Max	Unit
V_{FM}	Diode Forward Voltage	I_F = 10 A	T_C = 25°C	-	1.9	2.5	V
			T_C = 125°C	-	1.7	-	
t_{rr}	Diode Reverse Recovery Time	I_F =10 A, di_F/dt = 200 A/μs	T_C = 25°C	-	34	-	ns
			T_C = 125°C	-	57	-	
Q_{rr}	Diode Reverse Recovery Charge		T_C = 25°C	-	41	-	nC
			T_C = 125°C	-	96	-	

Typical Performance Characteristics

Figure 1. Typical Output Characteristics

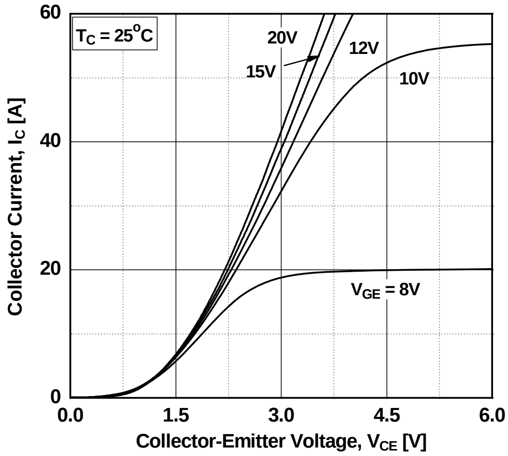


Figure 2. Typical Output Characteristics

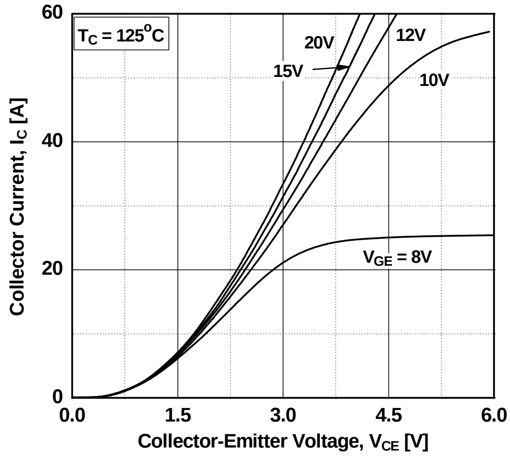


Figure 3. Typical Saturation Voltage Characteristics

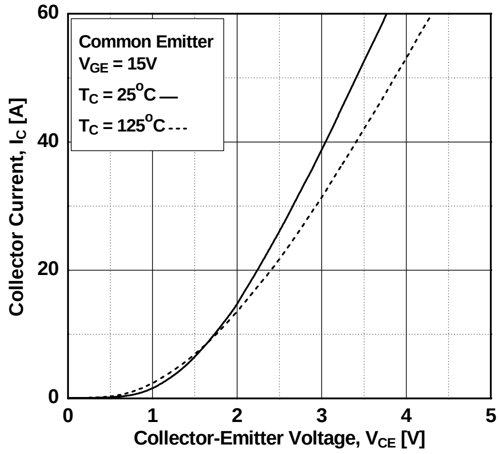


Figure 4. Transfer Characteristics

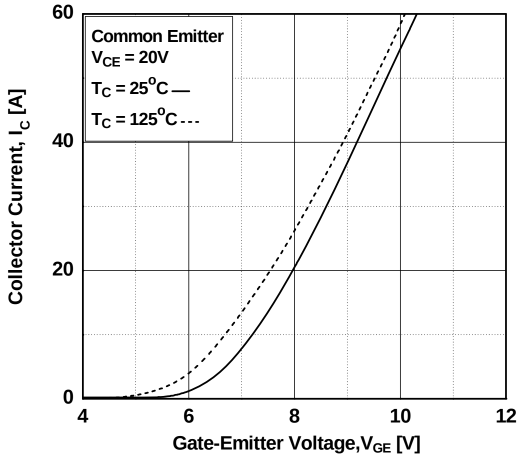


Figure 5. Saturation Voltage vs. Case Temperature at Variant Current Level

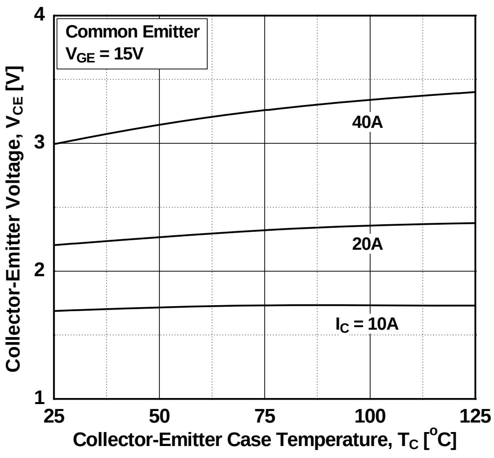
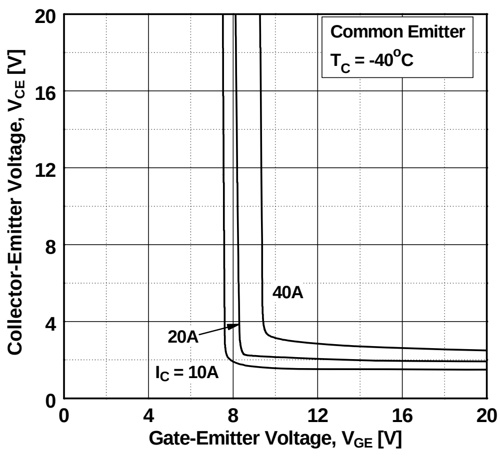


Figure 6. Saturation Voltage vs. V_{GE}



Typical Performance Characteristics

Figure 7. Saturation Voltage vs. V_{GE}

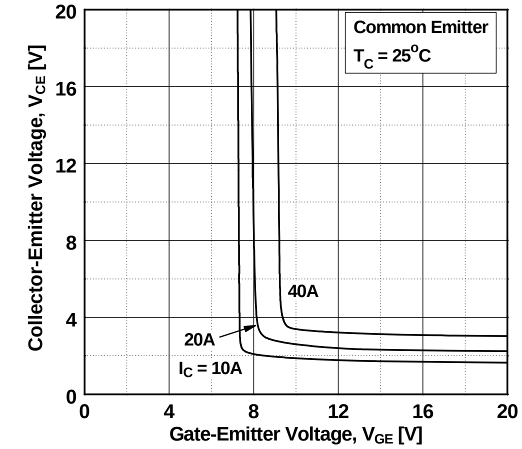


Figure 8. Saturation Voltage vs. V_{GE}

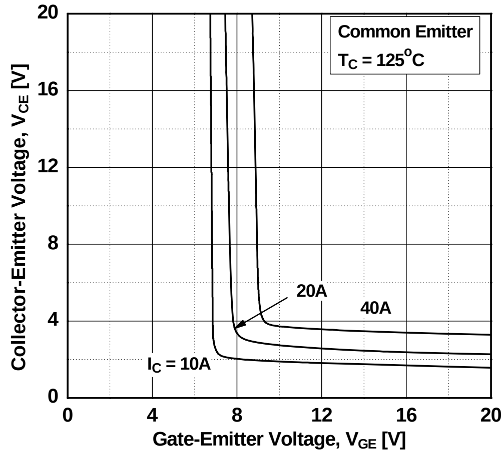


Figure 9. Capacitance Characteristics

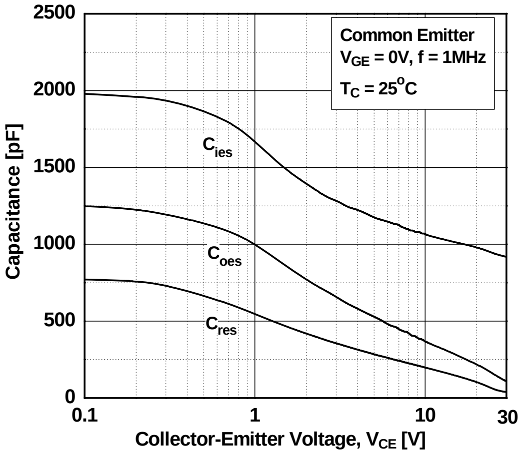


Figure 10. Gate charge Characteristics

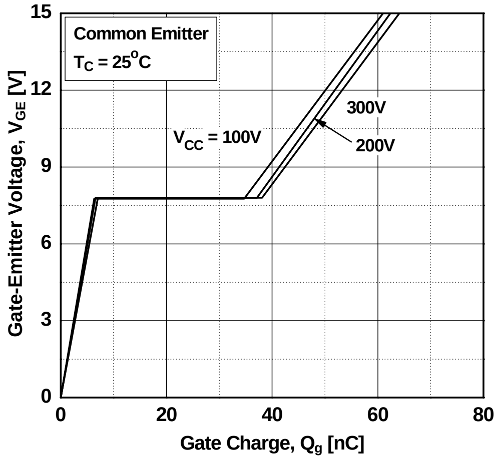


Figure 11. SOA Characteristics

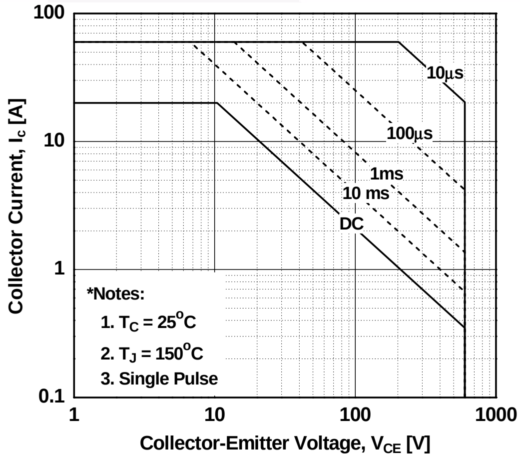
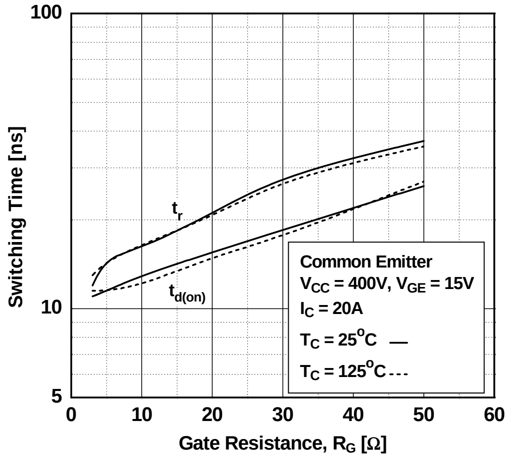


Figure 12. Turn-on Characteristics vs. Gate Resistance



Typical Performance Characteristics

Figure 13. Turn-off Characteristics vs. Gate Resistance

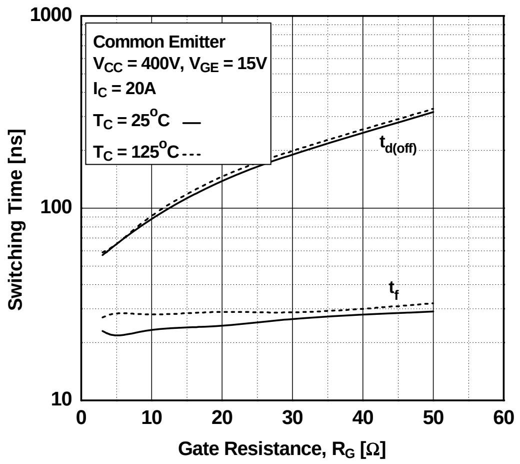


Figure 14. Turn-on Characteristics vs. Collector Current

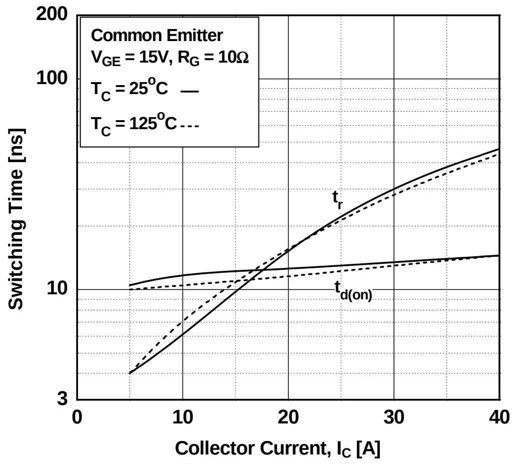


Figure 15. Turn-off Characteristics vs. Collector Current

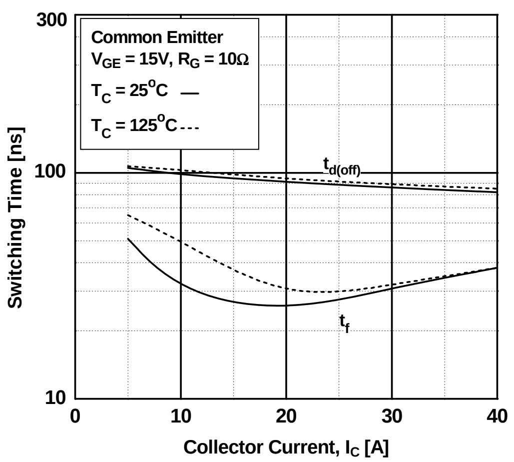


Figure 16. Switching Loss vs. Gate Resistance

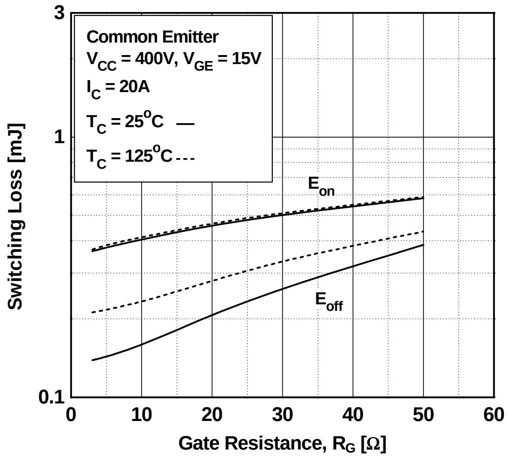


Figure 17. Switching Loss vs. Collector Current

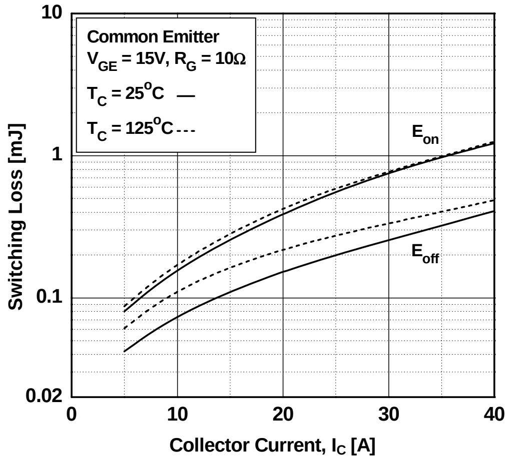
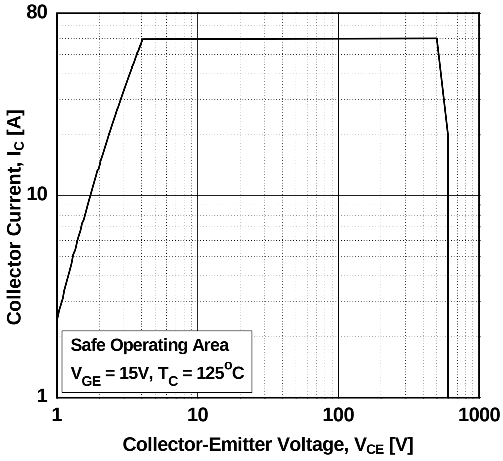


Figure 18. Turn off Switching SOA Characteristics



Typical Performance Characteristics

Figure 19. Forward Characteristics

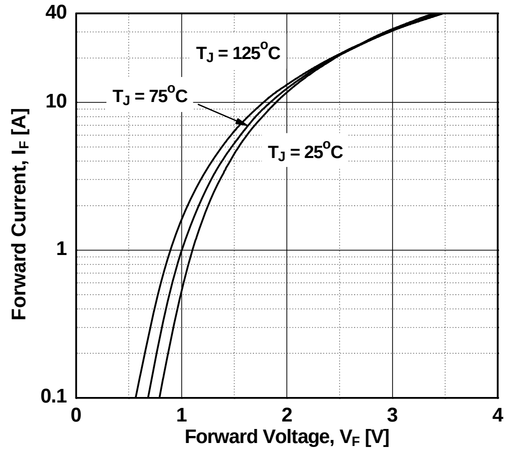


Figure 20. Reverse Current

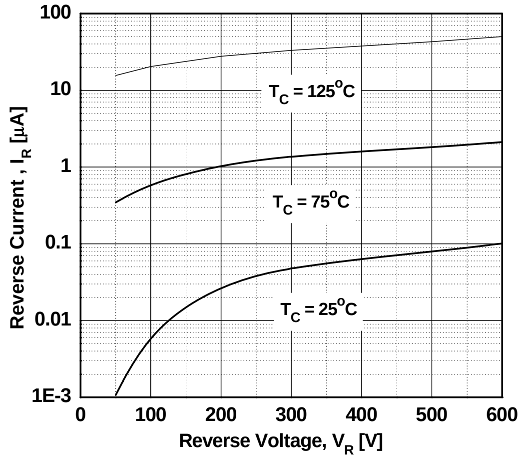


Figure 21. Stored Charge

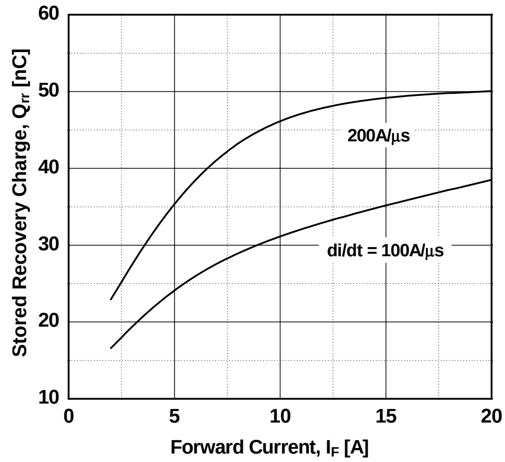


Figure 22. Reverse Recovery Time

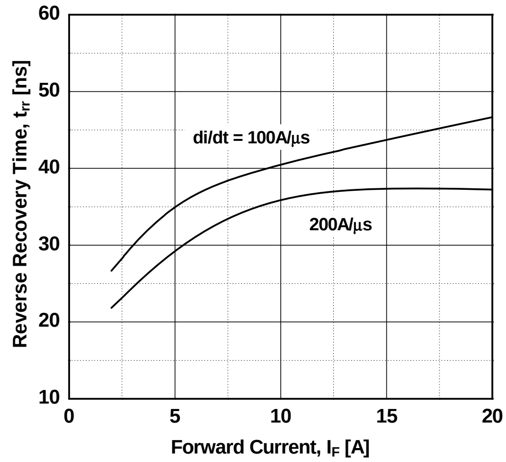
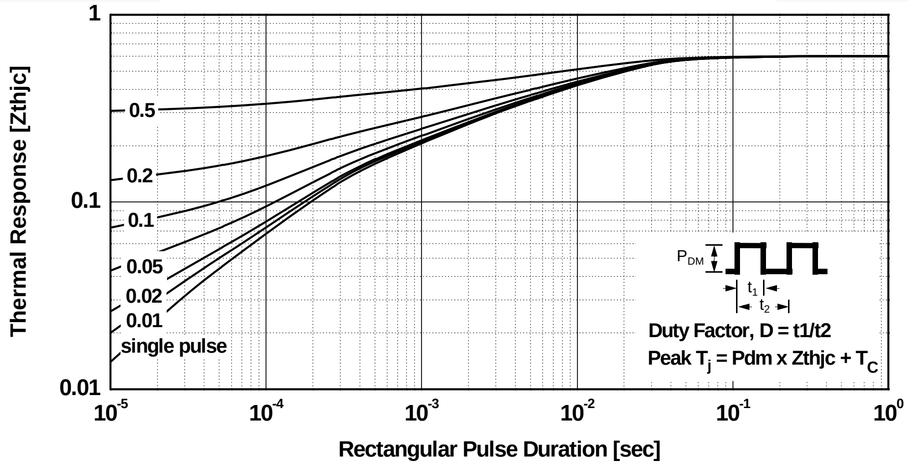


Figure 23.Transient Thermal Impedance of IGBT



Mechanical Dimensions

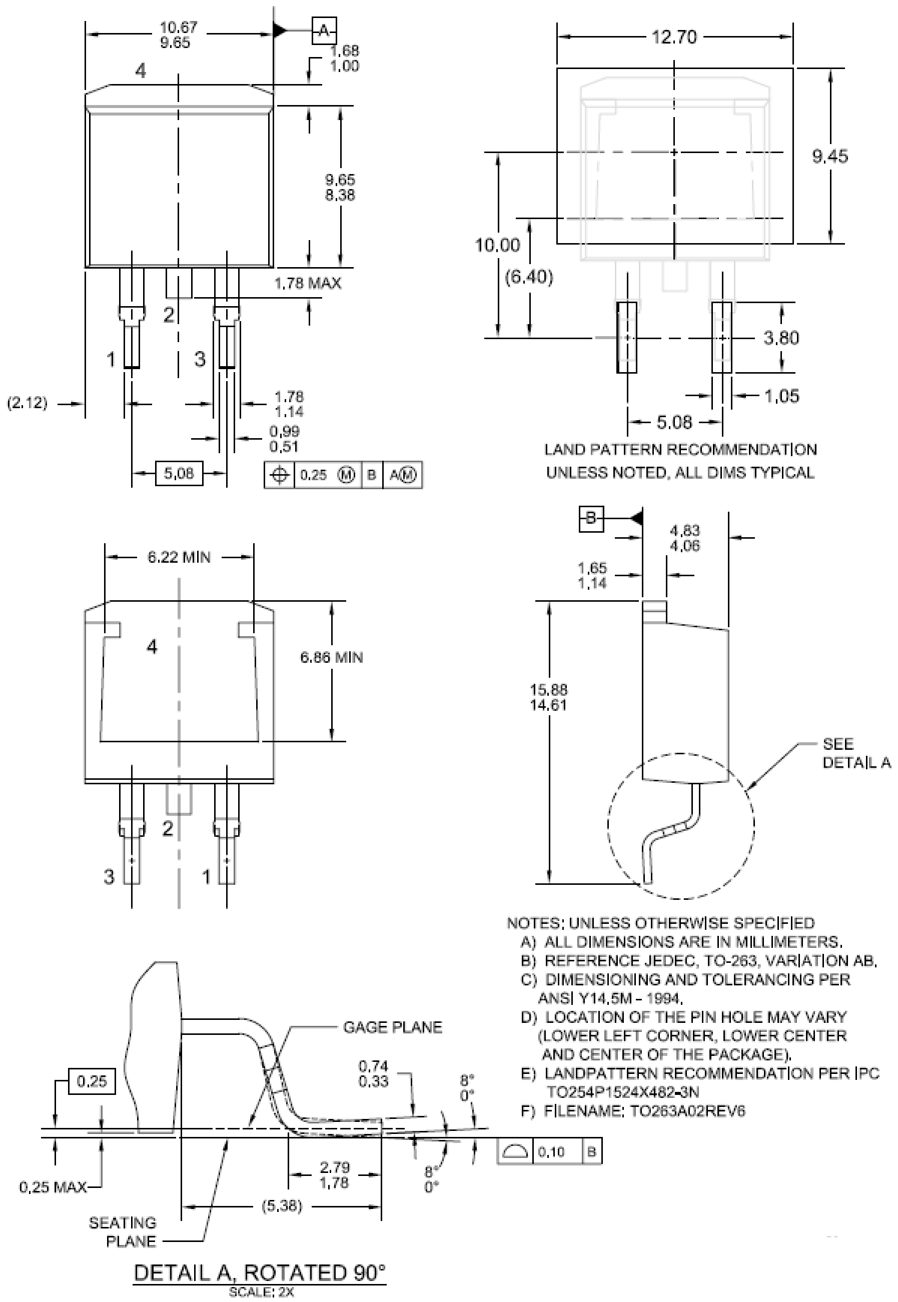


Figure 24. TO-263 2L (D2PAK) - 2LD,TO263, SURFACE MOUNT

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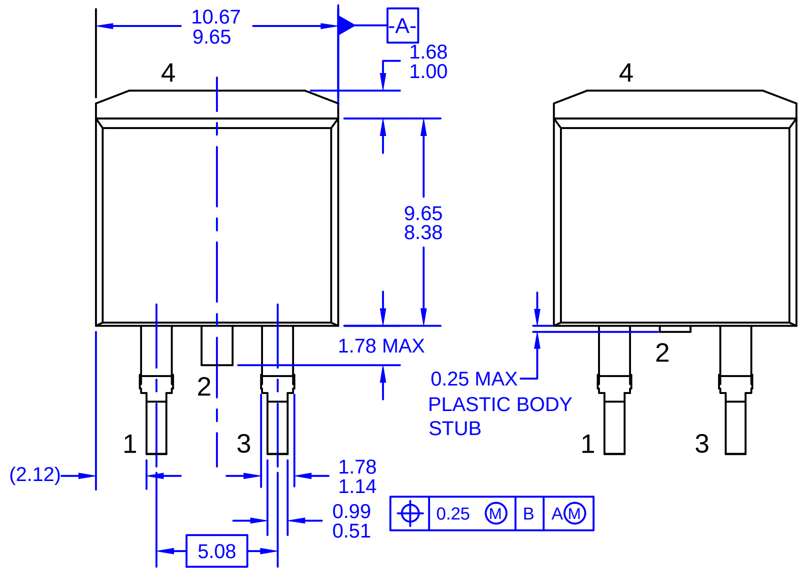
PRODUCT STATUS DEFINITIONS

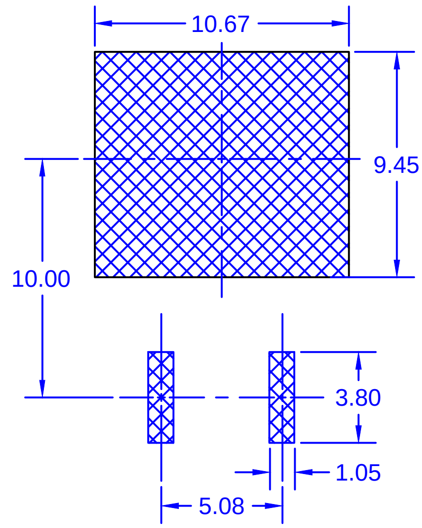
Definition of Terms

Datasheet Identification	Product Status	Definition
Advance Information	Formative / In Design	Datasheet contains the design specifications for product development. Specifications may change in any manner without notice.
Preliminary	First Production	Datasheet contains preliminary data; supplementary data will be published at a later date. Fairchild Semiconductor reserves the right to make changes at any time without notice to improve design.
No Identification Needed	Full Production	Datasheet contains final specifications. Fairchild Semiconductor reserves the right to make changes at any time without notice to improve the design.
Obsolete	Not In Production	Datasheet contains specifications on a product that is discontinued by Fairchild Semiconductor. The datasheet is for reference information only.

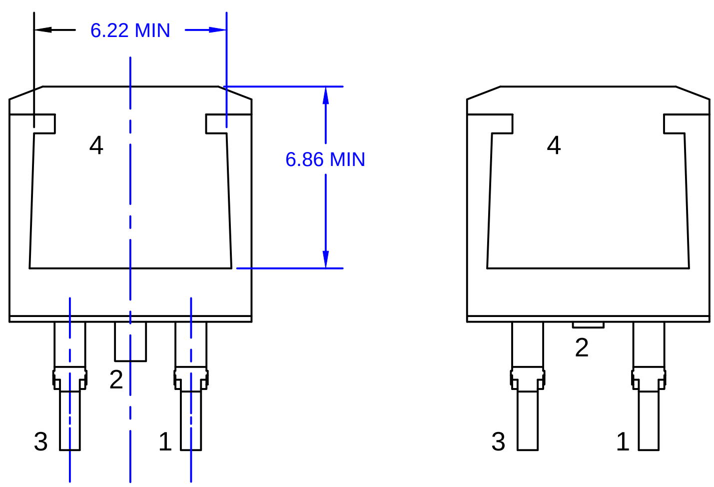
Rev. I73



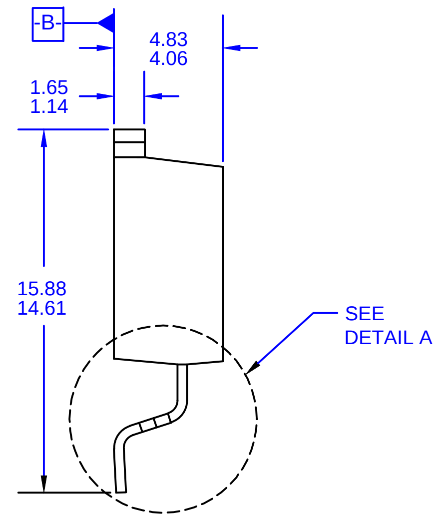
FRONT VIEW - DIODE PRODUCTS VERSION
ALTERNATIVE SUPPLIER DETAIL

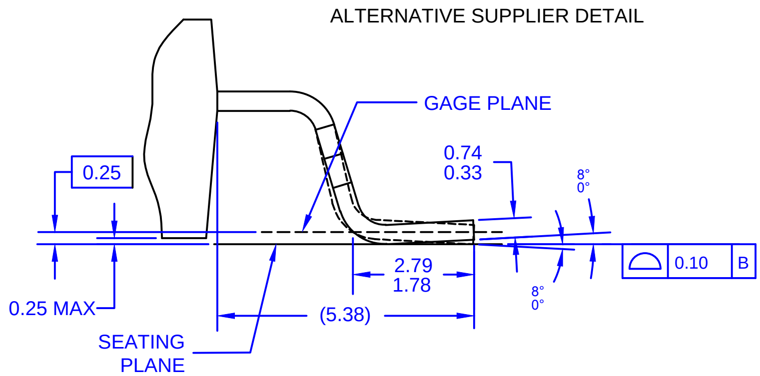


LAND PATTERN RECOMMENDATION
UNLESS NOTED, ALL DIMS TYPICAL



BACK VIEW - DIODE PRODUCTS VERSION
ALTERNATIVE SUPPLIER DETAIL





DETAIL A, ROTATED 90°
SCALE: 2X

NOTES: UNLESS OTHERWISE SPECIFIED
A) ALL DIMENSIONS ARE IN MILLIMETERS.
B) REFERENCE JEDEC, TO-263, VARIATION AB.
C) DIMENSIONING AND TOLERANCING PER DIMENSIONING AND TOLERANCING PER ASME Y14.5 - 2009.
D) LOCATION OF THE PIN HOLE MAY VARY (LOWER LEFT CORNER, LOWER CENTER AND CENTER OF THE PACKAGE).
E) LANDPATTERN RECOMMENDATION PER IPC TO254P1524X482-3N
F) FILENAME: TO263A02REV8

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